

BOARD-TO-BOARD HEADERS & RECEPTACLES





TE CONNECTIVITY (TE) MODII DBL VER OPN RCPT AS 8X2

AMPMODU | AMPMODU

281352-2

TE Internal Number: 281352-2

Always EU RoHS/ELV Compliant

Connector Style Receptacle Centerline 2.54 mm [.1 in]

Number of Positions 16

Packaging Method Reel

Contact Mating Area Plating Material Gold

Product Specifications

Product Specification

AMPMODU MOD II Interconnection System

PDF **English**

Please review product documents or contact us for the latest agency approval information.

Product Type Features	Connector Style	Receptacle
	PCB Mounting Orientation	Vertical
	Row-to-Row Spacing	2.54 mm [.1 in]
	Applies To	Printed Circuit Board
	Product Type	Connector
	Profile	Standard
	Series	AMPMODU, MOD II
	Sealed	No
	Connector Type	Connector Assembly
Configuration Features	Number of Positions	16
	Number of Rows	2
	Stackable	Yes
Electrical Characteristics	Insulation Resistance (M Ω)	5000

Contact Features	Contact Mating Area Plating Material	Gold
	Contact Mating Area Plating Thickness (µin)	15
	Contact Current Rating (A)	3
	Contact Type	Socket
	Contact Configuration	Dual Tine
	Solder Tail Contact Plating Material	Gold Flash over Nickel
	Contact Base Material	Phosphor Bronze
	T M. I. L. 200	
Termination Features	Termination Method to PC Board	Through Hole - Solder
	Termination Post Length	3.5 mm [.138 in]
Mechanical Attachment	PCB Mount Retention	Without
Housing Features	Centerline	2.54 mm [.1 in]
	Housing Material	Thermoplastic
	Housing Color	Black
	Housing Entry Style	Closed Entry
Dimensions	Height	8.7 mm [.343 in]
Usage Conditions	High Temperature Compatible	No
Industry Standards	MIL-C-55032	No
Packaging Features	Packaging Method	Reel
	Packaging Quantity	800
Product Compliance	Statement of Compliance	

VIEW ALL PRODUCT COMPLIANCE